



P/N 97-56001 Motorola DSP56000/001 QFP-to-PGA Adapter

FEATURES

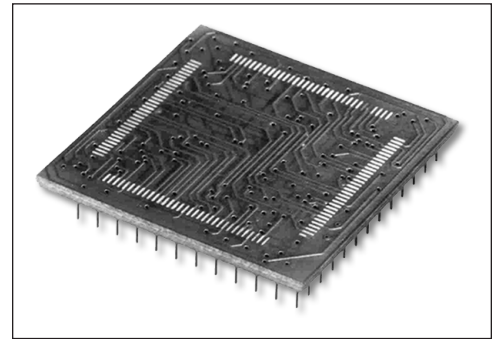
- Convert surface-mount QFP packages to a 13x13 PGA footprint.
- Reduce costs by using less-expensive QFP packages to replace PGA footprints in existing designs.
- Pins are mechanically fastened and soldered to board using Aries' patented process, creating a reliable electrical connection and rugged contact.
- Consult factory for Panelized Form or for mounting of consigned chips.

GENERAL SPECIFICATIONS

- ADAPTOR BODY: FR-4 with 1-oz. Cu traces
- PADS: finished with ENIG (Immersion Au over Electroless Ni) to eliminate coplanarity concerns and solder bridges associated with hot air solder leveling
- PINS: Brass 360 1/2-hard per UNS C36000, ASTM B16/B16M
- PIN PLATING: 200 μ [5.08 μ] Sn/Pb 93/7 per ASTM B579-73 over 100 μ [2.54 μ] Ni per SAE AMS-QQ-N-290
- OPERATING TEMPERATURE: 221°F [105°C]

MOUNTING CONSIDERATIONS

- SUGGESTED PCB HOLE SIZE: 0.028 $\pm$ 0.003 [0.71 $\pm$ 0.08] dia.
- Will Plug into standard PGA socket



CUSTOMIZATION: In addition to the standard products shown on this page, Aries specializes in custom design and production. Special materials, platings, sizes, and configurations can be furnished, depending on the quantity. **NOTE:** Aries reserves the right to change product general specifications without notice.

ORDERING INFORMATION

P/N 97-56001 QFP-to-PGA 13x13 Adapter

P/N 97-56001-P QFP-to-PGA 13x13

Panelized Form

P/N 100-PGM13069-30 QFP-to-PGA 13x13

Wire Wrap

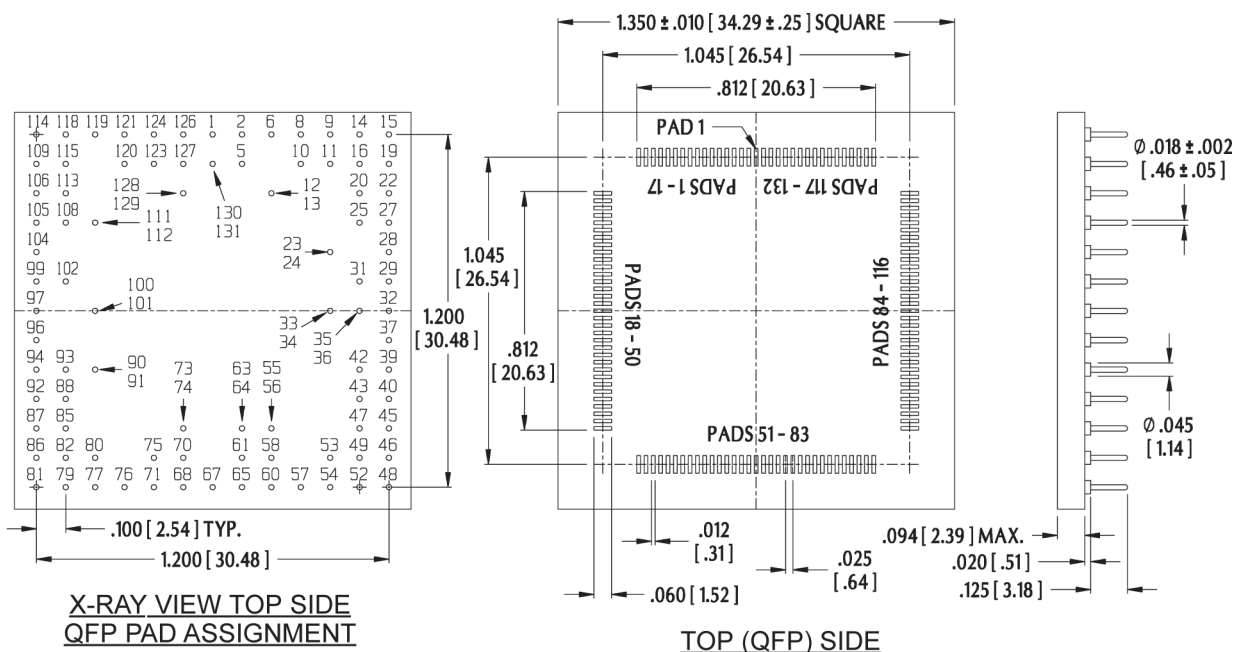
ALL DIMENSIONS: INCHES [MILLIMETERS]

ALL TOLERANCES: $\pm$ 0.005 [0.13] UNLESS OTHERWISE SPECIFIED

ROW-TO-ROW $\pm$ 0.003 [$\pm$ 0.08]

PIN-TO-PIN $\pm$ 0.003 [$\pm$ 0.08] NON-CUMULATIVE

CONSULT FACTORY FOR OTHER SIZES AND CONFIGURATIONS



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